



Final Product/Process Change Notification

Document #:FPCN25729XAB

Issue Date:06 Oct 2025

Title of Change:	Wafer Fab Site Addition of onsemi Bucheon, Korea as alternate fab for ESD and Surge Protection Products.																																		
Proposed First Ship date:	13 Jan 2026 or earlier if approved by customer																																		
Contact Information:	Contact your local onsemi Sales Office																																		
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.																																		
Additional Reliability Data:	Contact your local onsemi Sales Office																																		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact																																		
Marking of Parts/ Traceability of Change:	Changed material can be identified by lot code																																		
Change Category:	Wafer Fab Change																																		
Change Sub-Category(s):	Datasheet/Product Doc change, Manufacturing Site Addition																																		
Sites Affected:																																			
onsemi Sites					External Foundry/Subcon Sites																														
onsemi Bucheon, Korea					None																														
Description and Purpose:																																			
onsemi wishes to inform customers it has qualified onsemi Bucheon, Korea wafer fab as an additional wafer fab site for ESD and Surge Protection products.																																			
Upon expiration of this Final Product Change Notification (FPCN), affected parts can be sourced from either onsemi Bucheon, Korea or LA Semiconductor wafer fab.																																			
There is no product marking changes as a result of this change.																																			
<table><thead><tr><th></th><th>From</th><th>To</th></tr></thead><tbody><tr><td>Fab Site</td><td>LA Semiconductor Idaho, United States</td><td>onsemi Bucheon, Korea, LA Semiconductor, Idaho, United States</td></tr></tbody></table>											From	To	Fab Site	LA Semiconductor Idaho, United States	onsemi Bucheon, Korea, LA Semiconductor, Idaho, United States																				
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Fab Site	LA Semiconductor Idaho, United States	onsemi Bucheon, Korea, LA Semiconductor, Idaho, United States																																	
The Junction Capacitance at 5 GHz for ESD9101P2T5G datasheet will be revised as below.																																			
<table><thead><tr><th rowspan="2">Parameter</th><th rowspan="2">Symbol</th><th rowspan="2">Conditions</th><th colspan="3">Before</th><th colspan="3">After</th><th rowspan="2">Unit</th></tr><tr><th>Min</th><th>Typ</th><th>Max</th><th>Min</th><th>Typ</th><th>Max</th></tr></thead><tbody><tr><td>Junction Capacitance</td><td>C_J</td><td>VR = 0 V, f = 5.0 GHz between I/O Pins and GND</td><td></td><td></td><td>0.45</td><td></td><td></td><td>0.47</td><td>pF</td></tr></tbody></table>										Parameter	Symbol	Conditions	Before			After			Unit	Min	Typ	Max	Min	Typ	Max	Junction Capacitance	C _J	VR = 0 V, f = 5.0 GHz between I/O Pins and GND			0.45			0.47	pF
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Reliability Data Summary:

QV DEVICE NAME: SZESD9101P2T5G

RMS: L100803

PACKAGE: SOD-923-2

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1@260°C		
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231

QV DEVICE NAME: ESD9M5.0ST5G

RMS: L97093

PACKAGE: SOD-923-2

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta=150°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1@260°C		
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

QV DEVICE NAME: SZCM1213A-04SO

RMS: L100795

PACKAGE: SC-74-6

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta=150°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1@260°C		
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

QV DEVICE NAME: SZNSP4201MR6T1G

RMS: S97122

PACKAGE: TSOP6

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta=150°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1@260°C		
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231



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Electrical Characteristics Summary:

Limits have been changed in datasheet as described in "Description and Purpose" section of FPCN document.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
NUP4114HMR6T1G	SZCM1213A-04SO, SZNSP4201MR6T1G
NUP2114UCMR6T1G	SZCM1213A-04SO, SZNSP4201MR6T1G
ESD9101P2T5G	SZESD9101P2T5G, ESD9M5.0ST5G

Appendix A: Changed Products

PCN#: FPCN25729XAB
Issue Date: Oct 06, 2025

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NUP4114HMR6T1G		SZCM1213A-04SO, SZNSP4201MR6T1G	#NONE	
NUP2114UCMR6T1G		SZCM1213A-04SO, SZNSP4201MR6T1G	#NONE	
ESD9101P2T5G		SZESD9101P2T5G, ESD9M5.0ST5G	#NONE	